PACKAGING ENGINEERING INTERN

Posting ID: IN20014026

Company: Texas Instruments

Position Type: Full-Time

College Major(s): Mechanical Engineering (ME), Electrical/Computer Engineering (EE/CpE)

Company Website: http://www.ti.com/

Work Location: Santa Clara, CA

Salary:

College Level(s): Undergraduate-Senior, Graduate Student, PhD. Student, Alumni

OVERVIEW

Texas Instruments Incorporated (TI) is a global semiconductor design and manufacturing company that develops analog ICs and embedded processors. By employing the world’s brightest minds, TI creates innovations that shape the future of technology. TI is helping about 100,000 customers transform the future, today. We’re committed to building a better future – from the responsible manufacturing of our semiconductors, to caring for our employees, to giving back inside our communities and developing great minds. Put your talent to work with us – change the world, love your job!

Roles and Responsibilities

SC Packaging, Strategic R&D, is looking for a qualified candidate,

Interface across various work areas and organizations to help with the design, development, and analysis of different semiconductor packaging technologies to enable differentiation for TI’s analog and embedded processing products.

Assignments may include participation in cross-functional teams to understand the impact of various package design elements on the cost and performance of wirebond and flip chip packages.

Develop low cost packaging solutions with work in Mechanical Design, Assembly Process Integration and Material Science.

Education and Qualifications

Currently pursuing a Master’s or Phd degree in Mechanical Engineering, Materials Science, Chemical Engineering or Electrical Engineering.

Minimum Cumulative 3.0 GPA
Preferred Skills
Strong Mechanical Design Engineering fundamentals including proficiency in drafting and 3D modeling tools like AutoCAD, CREO, SOLIDWORKS, PROE.

Semiconductor packaging knowledge is preferred (processes, assembly, reliability, materials, characterization, FA)

Basic knowledge of Semiconductor Device Physics (MOSFET’s, BJT’s, CMOS etc)

Electrical modeling knowledge preferred (ex. Q3D, HFSS, ADS, SPICE, R3D)

Demonstrated analytical and problem solving skills

Strong written and verbal communication skills

Ability to work in teams and collaborate effectively with people in different functions

How to Apply